BONDING +
SEALING +
ENCAPSULATION

Kisling

8702

High-performance, one-component, non-curingthermal paste for challenging power electronics.

Our innovative filler matrix also provide the ideal basis for demanding heat-conducting pastes. These are characterised by high thermal conductivity and simultaneous outstanding workability, and are thus serious contributors to optimal thermal management. At the same time, they offer high levels of electrical insolation while not relying to any extent on silicones or solvents.

8702 is a high-performance, one-component, non-curing thermal paste. It stands out due to its high thermal conductivity of 2W/mK and its long-term stability in operation. The paste is ideal in the area of power electronics, where high heat dissipation or component cooling is required.

8702

+ 1K Thermal Paste
+ Thixotropic
+ No drying out
+ Thermal conductiviy 2,0W/mK
+ Silicone-free

Specifications	
Product category	Encapsulants | Thermal paste
Chemical base	1K Paste
Color	Natural (Cream)
Density [g/cm3]	2.20 – 2.50
Viscosity [mPas]	150 000 – 200 000
Temperature range [°C]	-60 – +200
Thermal conductivity [W/mK]	2.0

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